



SMD Mount Receptacle

Part No: RECE.20279.001E.01

Description:

SMD U.FL Compatible Receptacle Compatible with I-PEX MHFI, I-PEX MHFII, I-PEX MHFHT, Hirose U.FL, UMC

Features:

Mating Height: 3mm Max Supplied on Tape & Reel 5000pcs per reel Dimensions: 3 x 3 x 1.25 mm Diameter: 2mm RoHS & Reach Compliant



1.	Introduction	3
2.	Specifications	4
3.	Connector Data	6
4.	Mechanical Drawing	7
5.	Footprint	8
6.	Solder Reflow Profile	9
7.	Packaging	10
	Changelog	12

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1.





Part of the Taoglas SMD Mount Receptacle, the RECE.20279.001E.01 is a 3-pad type wire-to-board SMD receptacle that is ultra-small, lightweight and low profile, 2.5mm max. With an operational frequency range of DC to 6 GHz the RECE.20279.001E.01 is gold plated to provide superior performance and allow for ease of mounting with the male RF connector.

Packaged on tape and reel, this receptacle is designed to be placed with automatic "pick and place" equipment for ease of assembly.

The RECE.20279.001E.01 acts as a 50 Ohm transmission line to connect the micro-miniature RF connector to the printed circuit board. It is fully compatible with I-PEX MHFI, I-PEX MHFII, I-PEX MHFHT, Hirose U.FL and all other available U.FL compatible connectors .

Applicable Technologies:

The RECE.20279.001E.01 receptacles are commonly integrated into cellular, GPS and wireless LAN modules.

For further information, please contact your regional Taoglas customer support team.



2. Specifications

Electrical		
Operation Frequency	DC to 6 GHz	
VSWR	1.3 Max at DC~3 GHz	
VSWK	1.4 Max at 3~6 GHz	
Nominal Impedance	50 Ohm	
Rated Voltage	60V AC	
Rated Current	1A Max.	
Contact Resistance	Subject mated contacts assembled in housing to 20mV Max. open circuit at 10mA Max	
Withstand Voltage	AC 200V/minute	
Insulation Resistance	Impressed voltage 100V DC for 1min Initial : 500M Ω Min. Final : 100M Ω Min.	
Dielectric Withstanding Voltage	200V AC for 1 minute	
Current leakage	0.5mA Max	
Temperature	-40 to +90°C	

Material		
Outer Contact	Copper Alloy (Au plating)	
Centre Contact	Copper Alloy (Au plating)	
Insulator	LCP UL94V-0	

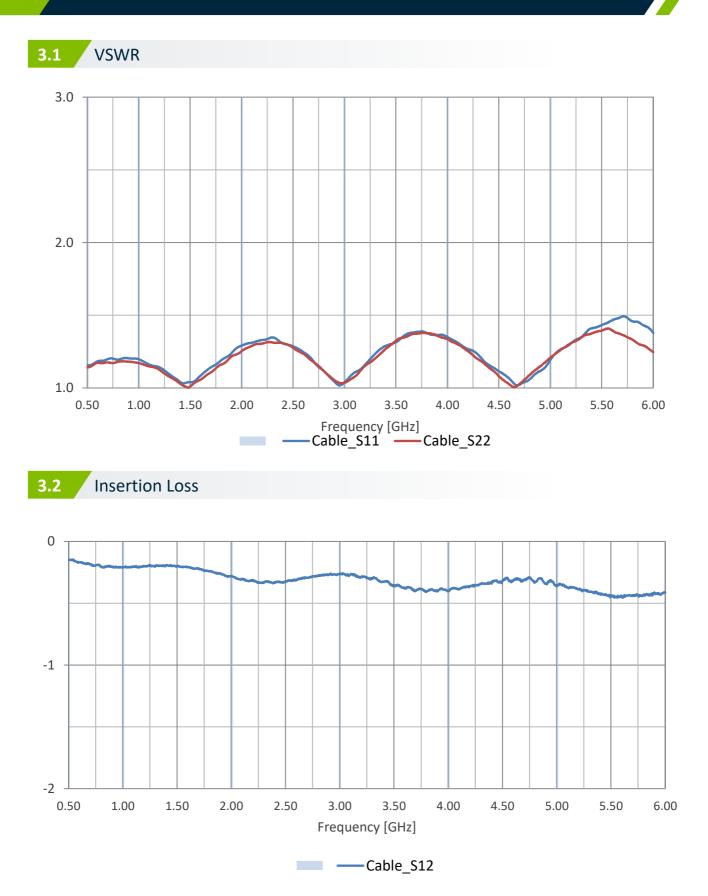
Environmental		
Durability per EIA-364-09C - (2-3 cycles per min @ 30 cycles)		
Vibration	10Hz -> 100Hz -> 10Hz for 20 mins.	
Peak value of acceleration	1.5mm or 59m/s2 (6G)	
Direction	3 Axis - 5 Cycles	
Mechanical Shock		
Accelerate Velocity	735m/s2 (75G)	
Waveform	Half-sine shock plus.	
Duration	11m sec.	
Direct Current	1mA	
Direction	In $\pm X$, $\pm Y$ and $\pm Z$ axes.	
Cycle	3 cycles for each direction, totally 18 cycles	



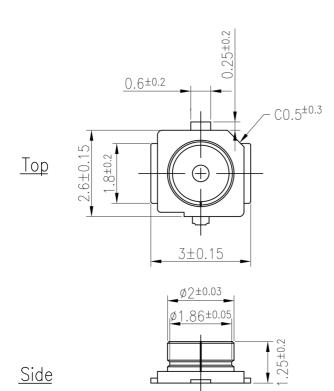
Thermal Shock (40°C for 30mins to 5~35°C for 5 minutes to 90°C for 30mins to 5~35°C for 5 minutes)		
Transition Time	5 minutes	
Cycles	5	
Humidity	90~95% RH	
Temperature	40+/- 2°C	
Duration	96 hours	
	Salt Water Spray	
Temperature	35+/- 2°C	
Salt Water Density	5+/-1% (by weight)	
Duration	48 Hours	
High temperature life	90+/- 2°C for 96 hours	
Cold temperature life	-40+/- 2°C for 96 hours	
	H2S gas	
Temperature	40+/-2°C	
Relative Humidity	80 +/-5% RH	
Gas H2S	3+/-1 ppm	
Duration	96 Hours	
Moister Sensitivity Level	3	

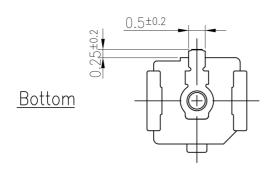


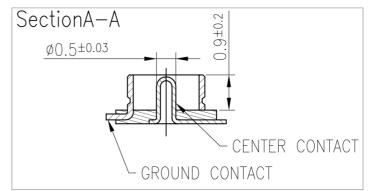
3. Connector Data





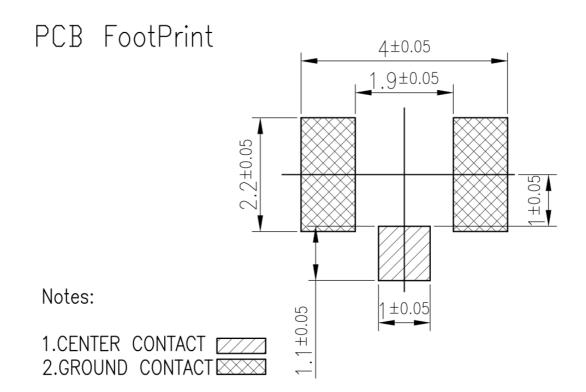








Footprint

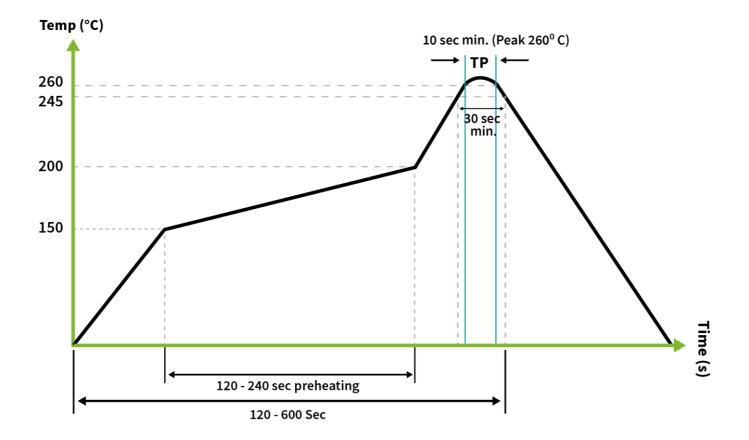


5.



Solder Reflow

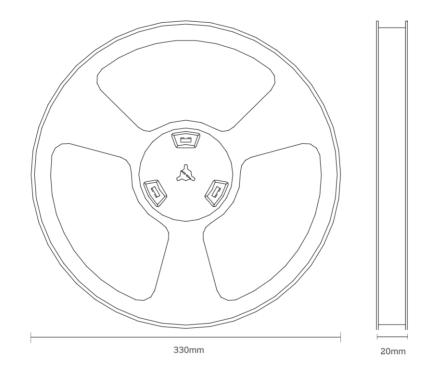
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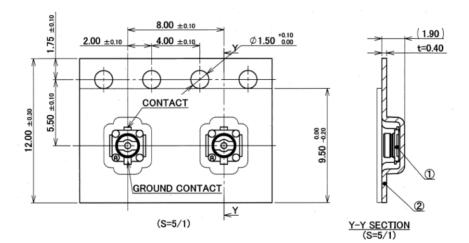




Packaging

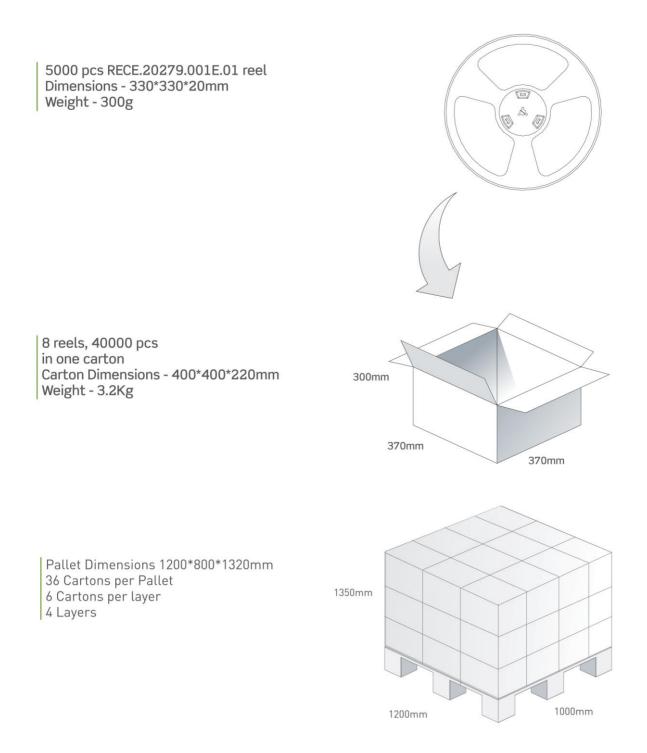
5000 pcs RECE.20279.001E.01 reel Dimensions - 330*330*20mm Weight -300g





7.







Changelog for the datasheet		
SPE-16-8-032 - RECE.20279.001E.01		
Revision: E (Current Version)		
Date:	2023-03-03	
Changes:	Updated descriptions	
Changes Made by:	Cesar Sousa	

Previous Revisions

Revision: D	
Date:	2022-01-27
Changes:	Updated descriptions
Changes Made by:	Gary West

Revision: C		
Date:	2021-07-15	
Changes:	Updated Solder Reflow Diagram & Adding MSL.	
Changes Made by:	Gary West	

R	Revision: B	
	Date:	2021-02-03
	Changes:	Following EC-20-8-036
	Changes Made by:	Jack Conroy

Revision: A (Original First Release)		
Date:	2016-04-21	
Notes:		
Author:	Jack Conroy	



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